SL05T1 Series

300 Watt, SOT-23 Low Capacitance TVS for High Speed Line Protections

This new family of TVS offers transient overvoltage protection with significantly reduced capacitance. The capacitance is lowered by integrating a compensating diode in series. This integrated solution offers ESD protection for high speed interfaces such as communication systems, computers, and computer peripherals.

Features

- TVS Diode in Series with a Compensating Diode Offers <5 pF Capacitance
- ESD Protection Meeting IEC 61000-4-2, 4-4, 4-5
- Peak Power Rating of 300 W, 8 × 20 μs
- Bi-Direction Protection Can Be Achieved By Using Two Devices
- Flammability Rating UL 94 V-0
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic case

FINISH: Corrosion resistant finish, easily solderable

MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:

260°C for 10 Seconds

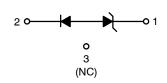
Package designed for optimal automated board assembly Small package size for high density applications Available in 8 mm Tape and Reel

Use the Device Number to order the 7 inch/3,000 unit reel. Replace the "T1" with "T3" in the Device Number to order the 13 inch/10,000 unit reel.



ON Semiconductor®

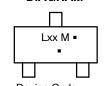
http://onsemi.com



MARKING DIAGRAM



SOT-23 (TO-236) CASE 318 STYLE 26



■ = Pb-Free Package (Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
SL05T1	SOT-23	3000/Tape & Reel
SL05T1G	SOT-23 (Pb-Free)	3000/Tape & Reel
SL12T1G	SOT-23 (Pb-Free)	3000/Tape & Reel
SL15T1	SOT-23	3000/Tape & Reel
SL15T1G	SOT-23 (Pb-Free)	3000/Tape & Reel
SL24T1	SOT-23	3000/Tape & Reel
SL24T1G	SOT-23 (Pb-Free)	3000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 3 of this data sheet.

SL05T1 Series

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 8x20 usec (Note 1) @ T _L ≤ 25°C	P _{pk}	300	W
IEC 61000-4-2 Level 4 Contact Discharge Air Discharge IEC 61000-4-4 EFT IEC 61000-4-5 Lightning	V _{pp}	±8 ±16 40 12	kV kV A A
Total Power Dissipation on FR-5 Board (Note 2) @ T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance Junction to Ambient	$R_{ hetaJA}$	556	°C/W
Total Power Dissipation on Alumina Substrate (Note 3) @ T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	417	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	– 55 to +150	°C
Lead Solder Temperature - Maximum (10 Second Duration)	TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

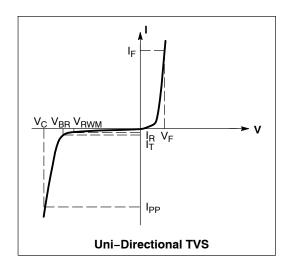
- 1. Non-repetitive current pulse per Figure 2
- 2. $FR-5 = 1.0 \times 0.75 \times 0.62$ in.
- 3. Alumina = 0.4 x 0.3 x 0.024 in., 99.5% alumina

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

UNIDIRECTIONAL

Symbol	Parameter			
I _{PP}	Maximum Reverse Peak Pulse Current			
V _C	Clamping Voltage @ I _{PP}			
V_{RWM}	Working Peak Reverse Voltage			
I _R Maximum Reverse Leakage Current @ \				
V _{BR}	Breakdown Voltage @ I _T			
I _T	Test Current			
ΘV _{BR} Maximum Temperature Coefficient of V _{BR}				
I _F Forward Current				
V _F	Forward Voltage @ I _F			
Z _{ZT}	Maximum Zener Impedance @ I _{ZT}			
I _{ZK}	Reverse Current			
Z _{ZK}	Maximum Zener Impedance @ I _{ZK}			

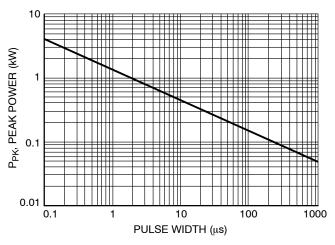


ELECTRICAL CHARACTERISTICS

				Breakdown Voltage (Note 4)		•	(Note 5)		Capacitance	
	Device	V _{RWM}	I _R @ V _{RWM}	V _{BR} @ 1 mA (Volts)		@ 1 A	@ 5 A	Max I _{PP}	@ V _R = 0 V,	1 MHz (pF)
Device	Marking	(V)	(μΑ)	Min	Max	(V)	(V)	(A)	Тур	Max
SL05	L05	5.0	20	6.0	8.0	9.8	11	17	3.5	5.0
SL12	L12	12	1.0	13.3	15.5	19	24	12	3.5	5.0
SL15	L15	15	1.0	16.7	18.5	24	30	10	3.5	5.0
SL24	L24	24	1.0	26.7	29	43	55	5.0	3.5	5.0

- 4. V_{BR} measured at pulse test current of 1 mA at an ambient temperature of 25°C
- 5. Surge current waveform per Figure 2

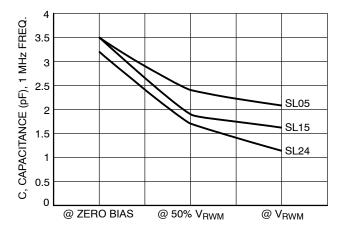
TYPICAL CHARACTERISTICS



PEAK VALUE I_{RSM} @ 8 μs 90 % OF PEAK PULSE CURRENT PULSE WIDTH (t_P) IS DEFINED 80 AS THAT POINT WHERE THE 70 PEAK CURRENT DECAY = 8 μs 60 HALF VALUE $I_{\mbox{RSM}}/2\ \mbox{@ 20}\ \mu \mbox{s}$ 50 40 30 20 10 0 0 20 40 80 t, TIME (μs)

Figure 1. Maximum Peak Power Rating

Figure 2. $8 \times 20~\mu s$ Pulse Waveform





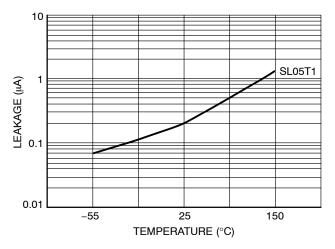


Figure 4. Typical Leakage Over Temperature

Applications Background

This new family of TVS devices (SL05T1 series) are designed to protect sensitive electronics such as communications systems, computers, and computer peripherals against damage due to ESD conditions or transient voltage conditions. Because of their low capacitance value (less than 5 pF), they can be used in high speed I/O data lines. Low capacitance is achieved by integrating a compensating diode in series with the TVS which is basically based in the below theoretical principle:

- Capacitance in parallel: CT = C1+C2+....+Cn
- Capacitance in series: 1/CT = (1/C1)+(1/C2)+....+(1/Cn) The Figure 5 shows the integrated solution of the SL05T1 series device:



Figure 5.

In the case that an over-voltage condition occurs in the I/O line protected by the SL05T1 series device, the TVS is reversed-biased while the compensation diode is forward-biased so the resulting current due to the transient voltage is drained to ground.

If protection in both polarities is required, an additional device is connected in inverse-parallel with reference to the first one, the Figure 6 illustrates the inverse-parallel connection for bi-directional or unidirectional lines:

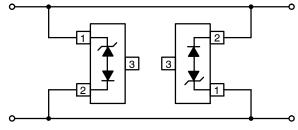


Figure 6.

An alternative solution to protect unidirectional lines, is to connect a fast switching steering diode in parallel with the SL05T1 series device. When the steering diode is forward-biased, the TVS will avalanche and conduct in reverse direction. It is important to note that by adding a steering diode, the effective capacitance in the circuit will be increased, therefore the impact of adding a steering diode must be taken in consideration to establish whether the incremental capacitance will affect the circuit functionality or not. The Figure 7 shows the connection between the steering diode and the SL05T1 series device:

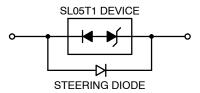


Figure 7.

Another typical application in which the SL05T1 series device can be utilized, is to protect multiple I/O lines. The protection in each of the I/O lines is achieved by connecting two devices in inverse–parallel. The Figure 8 illustrates how multiple I/O line protection is achieved:

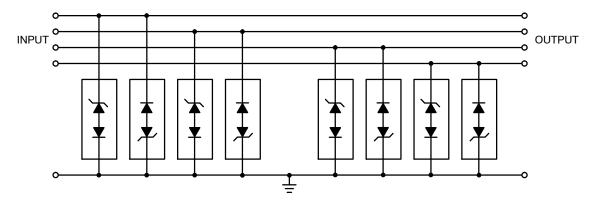


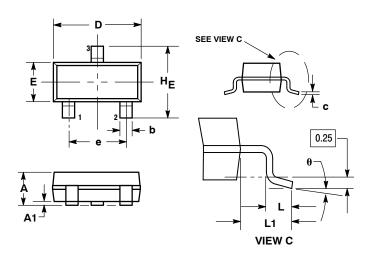
Figure 8.

For optimizing the protection, it is recommended to use ground planes and short path lengths to minimize the PCB's ground inductance.

SL05T1 Series

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AP**



NOTES

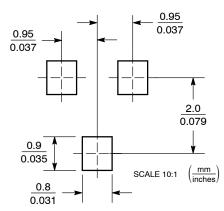
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	M	ILLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.040	0.044	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.018	0.020	
С	0.09	0.13	0.18	0.003	0.005	0.007	
D	2.80	2.90	3.04	0.110	0.114	0.120	
E	1.20	1.30	1.40	0.047	0.051	0.055	
е	1.78	1.90	2.04	0.070	0.075	0.081	
L	0.10	0.20	0.30	0.004	0.008	0.012	
L1	0.35	0.54	0.69	0.014	0.021	0.029	
HE	2.10	2.40	2.64	0.083	0.094	0.104	
θ	0°		10°	0°		10°	

STYLE 26: PIN 1. CATHODE 2. ANODE

3. NO CONNECTION

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, ON semiconductor and war registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC wors the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent—Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implications the policy of other applications intended to surgical implication in which the failure of the SCILLC product could create a situation where surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Literature Distribution Center for ON Semiconductor

P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative